

## APPENDIX

## Changes to Claims:

The following is a marked-up version of the amended claim:

1. (Amended) A method of manufacturing a semiconductor device comprising:  
a first step of interposing a first adhesive portion of an adhesive between a surface of a substrate on which an interconnect pattern is formed and a surface of a semiconductor chip on which electrodes are formed, and interposing a second adhesive portion of the adhesive formed next to said first adhesive portion and on at least a part of a lateral surface of said semiconductor chip; and  
a second step in which pressure is applied between said semiconductor chip and said substrate, said interconnect pattern and said electrodes are electrically connected, and said adhesive is caused to surround at least a part of the lateral surface of said semiconductor chip, at least a part of said second adhesive portion having a thickness greater than the first adhesive portion.